

Abstract of the Disclosure

An input output ring for a semiconductor device is disclosed that uses power buffers having widths that vary from the widths of the input and output buffers. In one embodiment, the pitches between bond pads are the same, in another embodiment the pitches between the bond pads can vary. In another embodiment, the number of bond pads is greater than the number of associated active buffer areas. By connecting two power bond pads to a common buffer the inductance associated with the buffer is reduced, thereby reducing the number of active buffers needed to be dedicated to providing power to the semiconductor device.

5